Travelling Merchant:_____

DATASHEET

Standard: **DP7X26000008**

Plot			The Label
Drew	Audited	Approved	Stamp, please! Thanks!
Amway.wei	Carry.Wang	James.Liu	
Date: 2017.05.23			

Guangdong Dapu Telecom Technology Co.,Ltd

Bldg13,.N.Ind.Zone,SSL Industry Park, Dongguan City, Guangdong Province, China

TEL：0086-0769-88010888 FAX：0086-0769-81800098

Bldg13,.N.Ind.Zone,SSL Industry Park,
Dongguan City, Guangdong Province,
PR China
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1、 Electrical Parameters

MODEL：DP7X26000008							
No.	Parameters	SYM.	Electrical Spec.				Notes
			Min.	Typ.	Max.	Units	
1	Nominal Frequency	FL	26.00			MHz	
2	Oscillation Mode	-	Fundamental			-	
3	Load Capacitance	CL	7			pF	
4	Frequency Tolerance	-	-20		+20	ppm	
5	Frequency Stability	-	-30		+30	ppm	
6	Operating Temperature	-	-20	~	+70	℃	
7	Aging	-	-5		+5	ppm	1st Year
8	Drive Level	DL	-		100	uW	
9	Shunt Capacitance C0	C0			5	pF	
10	Resonance Resistance	-		-	35	Ω	
11	Insulation Resistance	IR	500			MΩ	
12	Storage Temperature Range	-	-40	~	+85	℃	

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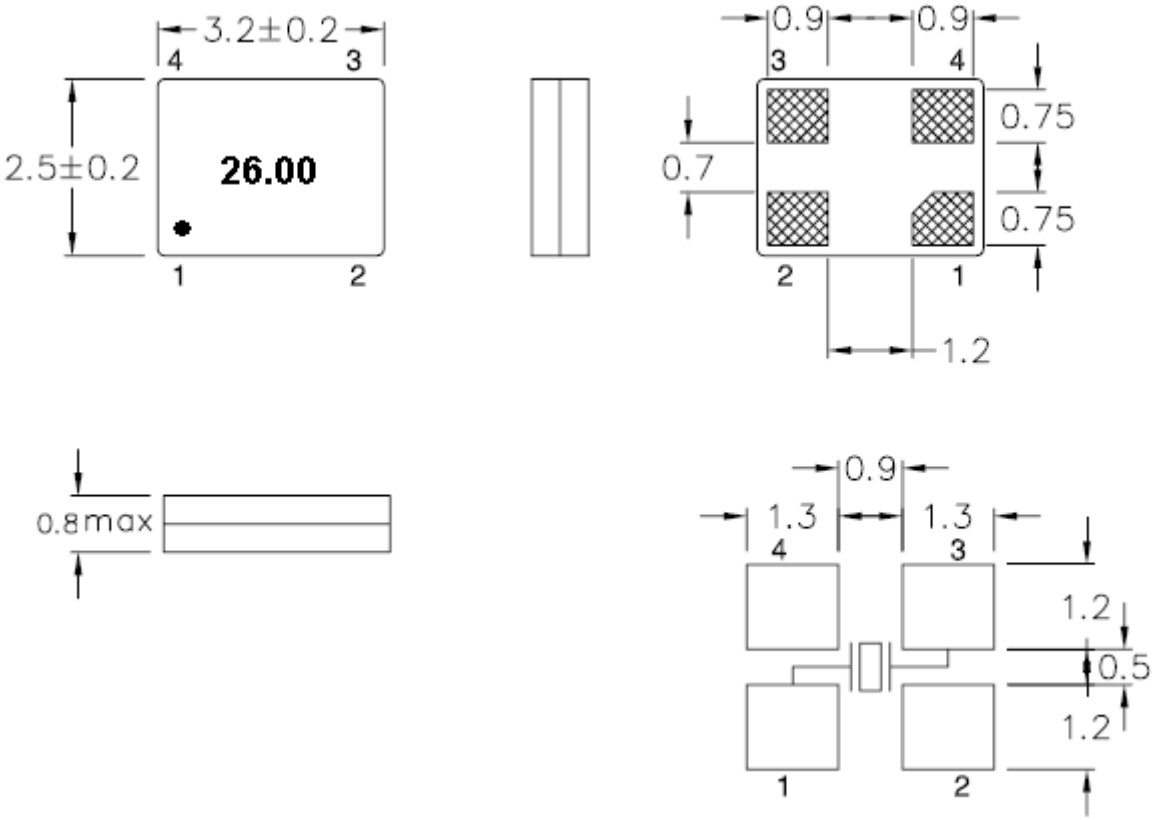
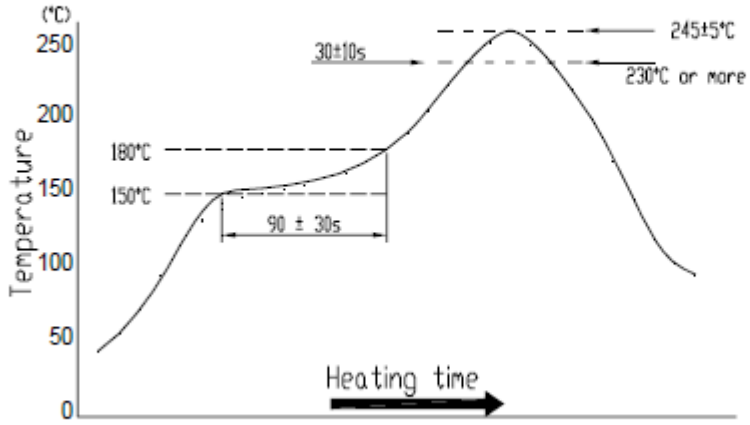
2、 Mechanical Structure(mm)



3、Recommended Reflow soldering condition (SMD)

Peak: 245±5℃ Soldering zone: 230℃ or more, 30±10s. Pre-heating zone 1: 150~180℃, 90±30s



Temperature profile for reflow soldering

Bldg13,.N.Ind.Zone,SSL Industry Park,
Dongguan City, Guangdong Province,
PR China
TEL:0086-0769-88010888
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4 、Reliability Specifications

NO.	PROCESS	SPECIFICATION	TEST METHOD
4.1	Temperature Cycle (GB/T 2423.22-2002, Method Nb)	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤10ohms.	10 cycles from -40°C to 85°C. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.2	Low Temperature Storage (GB/T 2423.1-2001, Method Aa)	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤10ohms.	Spending 72 hrs at -40°C±3°C constant temperature. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.3	High Temperature Storage (GB/T 2423.2-2001, Method Ba)	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤10ohms.	Spending 72 hrs at 85°C±3°C constant temperature. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.4	Humidity (GB/T 2423.3-2006, Method Cab)	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤10ohms.	Spending 96 hrs at 40 °C ± 3 °C, with 93 %R.H, Then keep the DUT in dry oven at 40 ± 5 °C for 24 hour. Measurement taken after DUT being left at room temperature for 1 to 2 hours.
4.5	Vibration (GB/T 2423.10-1995, Method Fc)	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤10ohms.	Apply 0.75mm vibration at sweep frequency 10~ 500 Hz, 10 cycles in each direction of 3 axis. Measurement taken after 1 hour.
4.6	Shock (GB/T 2423.5-1995, Method Ea)	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤10ohms.and exhibit no visible damage.	Peak 1000m/s2, normal width 6ms half sine wave form, 3.7m/s, 3 perpendicular axis of samples, 3 cycles / direction, total 18 cycles. Measurement taken after 1 hour.
4.7	Drop (GB/T 2423.8-1995, Method Ed)	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤10ohms.and exhibit no visible damage.	Free drop to the steel plate with thickness of 3 mm from 1.00 m heights for 3 times.
4.8	Solderability (IEC60068-2-58,Test Td:)	Terminals shall be covered more then 95% with solder.	Passed through the re-flow oven under the following condition. Preheat 150 to 180°C for 60 to 120sec, and soldering time for 20s ± 5s at 235°C, peak soldering time for 10s ± 1s betweein 240 and 250°C. There is no need to do functional test. 8-12X magnifier.
4.9	Terminal Strength (JIS-C-6429 Method 1 & 2)	No visible damage	Mount on a glass-epoxy board (100x50x1.6mm), then bend to 2mm displacement (velocity 1mm/sec) and keep for 5 seconds. or pulling force 10N for at least 60 seconds.
4.10	Resistance to solvent (GB/T	Mark in focus	Immersion in cleaning solvent for 5±0.5min.
4.11	Resistance to Soldering Heat (IEC60068-2-58,Test Td: Table 4)	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤10ohms.	Passed through the re-flow oven under the following condition. Preheat 150 to 180°C for 60 to 120sec, and sodering time for 60s max at 235°C, peak soldering time for 20s max at 265°C max. Measurement taken after DUT being left at room temperature for at least 2 hours.

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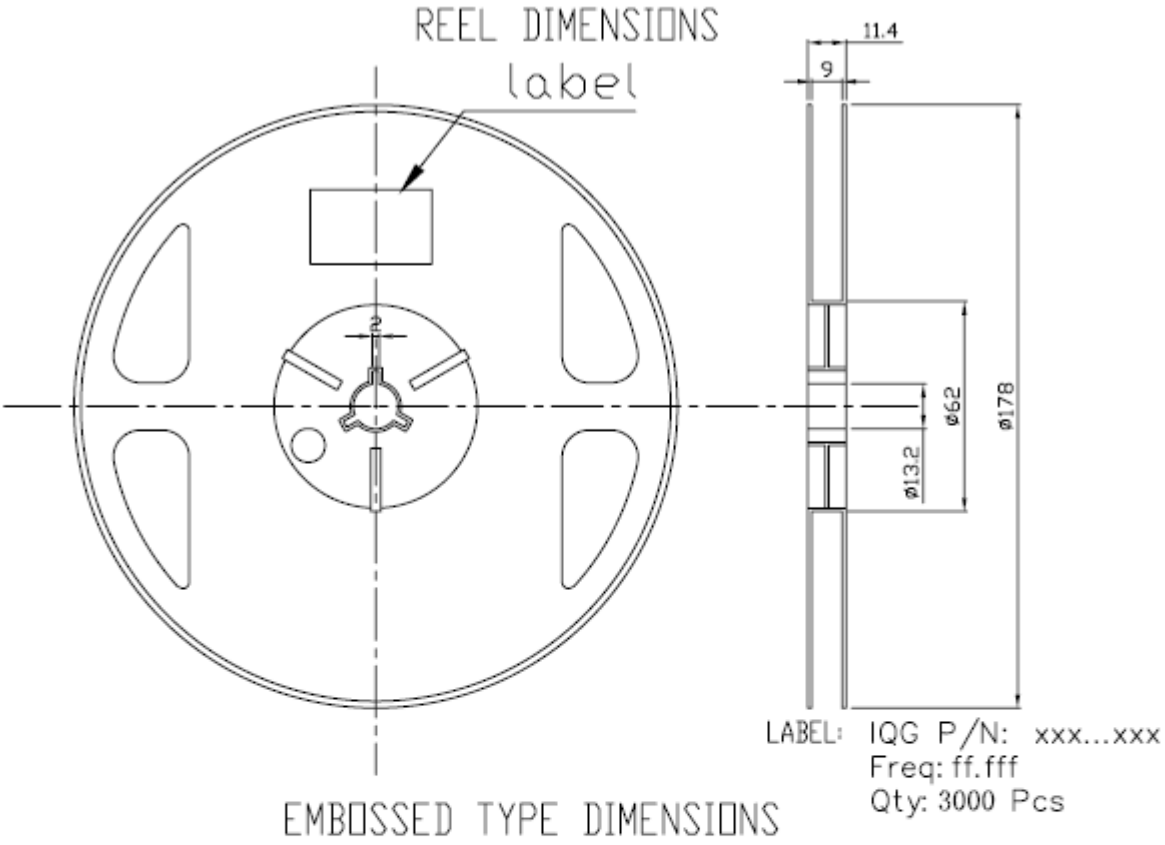
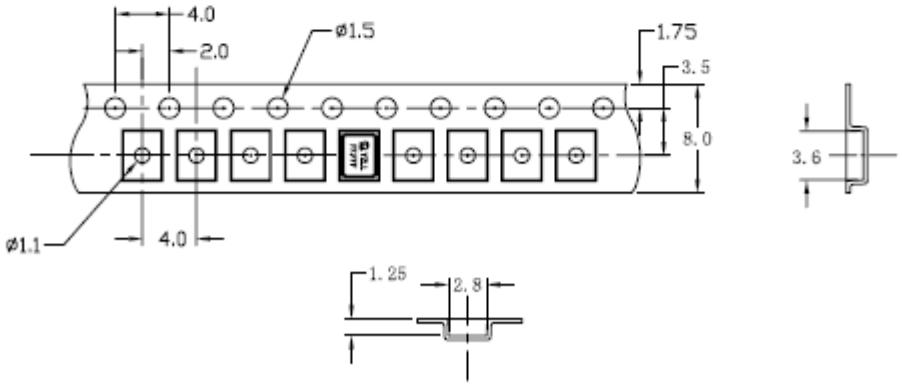
5、Package: Tape & Reel (mm)



EMBOSSED TYPE DIMENSIONS



USER FEED DIRECTION